PCN Number:		20150603000			F	PCN Date	: 06/08/2015				
Titl	e:	of GT	BF as A	ddi	tional	Assembly/Test	Site fo	or S	elect Devi	ices	
Cus	stome	Contact:	PCN Manager			Dept:		Qualit	ality Services		
Proposed 1 st Ship Date			e:	09/08/	'20	Estimated Sample Availability:			Date Provided at Sample request		
Change Type:											
Assembly Site						Des	sign			Wafer Bu	ump Site
Assembly Process						Dat	a Sheet			Wafer Bu	ump Material
\boxtimes	Assen	nbly Materials				Par	t number chan	ge		Wafer Bu	ump Process
Mechanical Specifical			ation	☐ Test Site			Wafer Fa	ab Site			
Packing/Shipping/Lab			belin	g		Tes	t Process			Wafer Fa	ab Materials
							·			Wafer Fa	ab Process
PCN Details											

Description of Change:

Qualification of GTBF as additional assembly and test site for Select Devices. Assembly differences are shown in the following table:

Group 1 Device:

<u> </u>				
	NFME	GTBF		
Mount Compound	SID# MC-05	SID# EY0000006		
Mold Compound	SID# R-12	SID# EN0000038		

Group 2 Device:

•	NFME	GTBF
Mount Compound	SID# MC-05	SID# EY0000006
Mold Compound	SID# R-12	SID# EN0000038
Wire type	Au	Cu

Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Assembly Site				
NFME	Assembly Site Origin (22L)	ASO: NFM		
GTBF (Great Team Backend Foundry)	Assembly Site Origin (22L)	ASO: GTF		

Sample product shipping label (not actual product label)





(1P) SN74LS07NSR (a) 2000 (D) 0336 31T)LOT: 3959047MLA 4W) TKY(1T) 7523483SI2 (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS

ASSEMBLY SITE CODES: NFME = E, GTBF = TBD

Group 1 Product Affected:					
TLV1117CKCS	UA78M05CKCS	UA78M08CKCS	UA78M33CKCS		
TLV1117CKCSE3	UA78M05CKCSE3	UA78M08CKCSE3	UA78M33CKCSE3		
TLV1117IKCS	UA78M05IKCS	UA78M12CKCS			
TLV1117IKCSE3	UA78M05IKCSE3	UA78M12CKCSE3			
Group 2 Product Affected:					
LM317KCS	LM317KCSE3				

Qualification Report Qualify GTBF as subcon A/T site for 3pin TO-220 KCS PWR Packages

Product Attributes

Attributes	Qual Device: LM317KCS
Assembly Site	GTBF
Package Family	TO-220
Flammability Rating	UL-V94-0
Wafer Fab Supplier	SFAB
Wafer Fab Process	Jl1

⁻ QBS: Qual By Similarity

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: LM317KCS
AC	Autoclave 121C	96 Hours	3/237/0
HAST	Biased HAST, 130C/85%RH	96 Hours	3/255/0
HTSL	High Temp. Storage Bake, 150C	1000 Hours	3/231/0
LI	Lead Fatigue	Leads	3/24/0
LI	Lead Pull to Destruction	Leads	3/24/0
MISC	Salt Atmosphere	Salt/Atmos	3/66/0
MQ	Manufacturability	(per mfg. Site specification)	3/Pass
PD	Physical Dimensions	(per mechanical drawing)	3/15/0
PKG	Lead Finish Adhesion	Leads	3/24/0
PKG	Solder Heat	10 sec	3/66/0
SD	Solderability	8 Hours Steam Age	3/66/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/273/0

⁻ Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com

⁻ Qual Device LM317KCS is qualified at Not Classified

⁻ The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

⁻ The following are equivalent HTSL options based on an activation energy of $0.7 \mathrm{eV}$: $150 \mathrm{C}/1 \mathrm{k}$ Hours, and $170 \mathrm{C}/420$ Hours

⁻ The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at TI's external Web site: http://www.ti.com/